



International Conference Wood Science and Engineering in the Third Millennium - ICWSE 2023

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Deadline for manuscript
submissions:

closed (31 January 2024)

Message from the Guest Editors

Dear Colleagues,

The International Conference Wood Science and Engineering in the Third Millennium (ICWSE), hosted by the Transilvania University of Brasov (Romania), Faculty of Furniture Design and Wood Engineering, has reached the 13th edition. The main scope of this conference is to provide a forum for discussion referring to the most recent advances in wood science and technology. The upcoming conference (ICWSE 2023) will take place between 2 and 4 November 2023. Over 80 participants from all over the world are expected at this event, to present their newest research achievements. Papers published under this special ICWSE 2023 issue will cover a range of 8 major topics which are listed as keywords below.

- wood structure and properties
- wood drying and heat treatments
- mechanical wood processing and quality
- wood-based materials
- wood preservation, modification, gluing and coating
- conservation-restoration of wooden objects
- furniture design
- wood constructions





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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